

IN THE CLAIMS:

Please cancel Claim 19 without prejudice.

Please amend the Claims as follows:

R3 1. (Amended) A miniaturized circuit housing to encapsulate and provide external contacts for at least one integrated circuit having circuit contact elements on a lower surface, the circuit housing comprising:

a housing floor comprising a lower surface which includes housing contact elements for making external contact and an upper surface which is electrically connected to the circuit contact elements on the lower surface of the circuit; and

a housing lid opposite the housing floor so as to press the circuit with the circuit contact elements resiliently against the upper surface of the housing floor with no permanent connection between the materials thereof

2. (Amended) The circuit housing of Claim 1, wherein the housing lid on its lower surface, which faces the circuit, comprises at least one spring element that presses the circuit against the housing floor.

3. (Amended) The circuit housing of Claim 2, wherein the at least one spring element is fixedly attached to the lower surface of the housing lid.

4. (Amended) The circuit housing of Claim 2, wherein the at least one spring element is loosely inserted between the housing lid and circuit. Fig 7

5. (Amended) The circuit housing of Claim 1, wherein the housing lid is flexible. Fig 8

6. (Amended) The circuit housing of Claim 1, further comprising a wall that substantially rigidly connects the floor and the lid of the housing to one another at their circumference so as to define an interior of the housing and tightly seals off the interior of the housing.

7. (Amended) The circuit housing of Claim 6, wherein the wall is formed as part of the housing floor or the housing lid and wherein the wall is sealed via a butt joint to the respective housing lid or housing floor in a gas-tight manner.

8. (Amended) The circuit housing of Claim 7, wherein the seal is formed by an external plastic encapsulation of at least the butt joint between the housing lid or housing floor and the wall. Fig 9

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9. (Amended) The circuit housing of Claim 6, wherein the interior of the housing is filled with an inert gas.

10. (Amended) The circuit housing of Claim 1, wherein the housing has a flat four-cornered shape, with a substantially level and rectangular housing floor and housing lid.

11. (Amended) The circuit housing of Claim 6, wherein the lid of the housing is rigidly constructed and joined to the wall

12. (Amended) The circuit housing of Claim 1, wherein the lid of the housing is constructed as a heat sink comprising area-increasing structures in order to cool the circuit.

13. (Amended) The circuit housing of Claim 2, wherein the ductility and shapes of the housing lid and the at least one spring element is selected such that the pressing force exerted by the housing lid and the at least one spring element between the circuit and the housing floor is such as to maintain electrical contact between the circuit contact elements and the housing floor.

14. (Amended) The circuit housing of Claim 1, wherein the housing contact elements are at least partially spherical.

15. (Amended) The circuit housing of Claim 1, wherein the housing contact elements are constructed substantially as contact pins or flat contact surfaces.

16. (Amended) The circuit housing of Claim 1, wherein the housing floor is constructed as at least a section of a circuit board.

17. (Amended) The circuit housing of Claim 1, wherein the upper surface of the housing floor is provided with inner housing contact surfaces configured as flat elevations so as to make internal contact with the circuit contact elements.

18. (Amended) The circuit housing of Claim 17, wherein the inner housing contact surfaces comprise gold and are formed by the stamping of bumps.

Please add the following new Claims:

20. (New) The circuit housing of Claim 6, further comprising a rigid covering wherein the rigid covering shields the lid of the housing such that externally applied forces are inhibited from being transmitted to the circuit.

21. (New) An electronic circuit housing for an integrated circuit chip positioned therein, the chip having chip contacts, the housing comprising:

a housing floor comprising a plurality of outer contacts disposed on a lower surface of the housing floor so as to provide external contact and in electrical contact with a corresponding plurality of inner contacts arranged to correspond to the chip contacts; and

a housing lid adapted to be attached to the housing floor so as to define the housing wherein the attachment of the housing lid to the housing floor induces an elastic pressure on the chip so as to create a compression contact between the chip contacts and the inner contacts.

22. (New) The circuit housing of Claim 21, wherein the elastic pressure arises from an elastic deformation of the housing lid upon attachment of the housing lid and the housing floor with the chip interposed therebetween.

23. (New) The circuit housing of Claim 21, further comprising at least one elastic element interposed between the housing lid and the chip.

24. (New) The circuit housing of Claim 23, wherein the at least one elastic element comprises a spring.

25. (New) The circuit housing of Claim 23, wherein the at least one elastic element comprises an elastomeric bulk material.

26. (New) The circuit housing of Claim 23, wherein the at least one elastic element is fixedly attached to the housing lid or the chip.

27. (New) The circuit housing of Claim 23, wherein the at least one elastic element is held in compression between the housing lid and the chip by the attachment of the housing lid to the housing floor.

28. (New) The circuit housing of Claim 21, wherein at least one of the outer contacts and the chip contacts comprise gold.